



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-06-16
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32G0B1CBU3	F8MI*467XXXZ	A	P1C7	2025-06-16
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	97	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFN	7x7	48	Flat	
Comment	Package : A0B9 UFQFPN 7X7X0.55 48L 0.5 MM PITCH 8202210			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-21st January 2025				Response
QUERY				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	F8MI*467XXXZ		97.1099		6000000.0	1000000.0				
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	3.963	mg	supplier	die	Silicon (Si)	7440-21-3		3.579	mg	903174	36856.41				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.018	mg	4567	186.37				
				supplier	metallization	Copper (Cu)	7440-50-8		0.163	mg	41105	1677.40				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.052	mg	13245	540.50				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	457	18.65				
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	457	18.65				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.042	mg	10505	428.68				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.105	mg	26490	1080.99				
				Glue Epoxy (OMI519)	M-011 Other inorganic materials	0.404	mg	supplier	Metals	Silver (Ag)	7440-22-4		0.323	mg	800000	3327.75
								supplier	Plastics/polymers	methylene diacrylate	42594-17-2		0.066	mg	164000	682.19
supplier	Polymers	Dicyclopentenyloxyethyl methacrylate	68586-19-6						0.010	mg	25000	103.99				
supplier	Polymers	Epoxyoctahydroxytrimethoxysilane	3388-04-3						0.002	mg	5000	20.80				
SVHC	Organic Compounds	Bis(o,o-dimethylbenzyl) peroxide	80-43-3						0.002	mg	5000	20.80				
supplier	Metals	Palladium (Pd)	7440-05-3						0.000	mg	1000	4.16				
Encapsulation (CEL-9240ZHF10W)	M-011 Other inorganic materials	35.017	mg					supplier	Glass	silica vitreous	60676-86-0		30.815	mg	880000	317319.98
				supplier	Epoxy Resin	Biphenyl epoxy resin	85954-11-6		1.751	mg	50000	18029.54				
				supplier	Phenol Resin	Phenolic resin	205830-20-2		1.366	mg	39000	14063.04				
				supplier	Epoxy Resin	Epoxy resin	Proprietary		0.700	mg	20000	7211.82				
				supplier	Additive	carbon black	1333-86-4		0.070	mg	2000	721.18				
				supplier	Metals	other	Proprietary		0.315	mg	9000	3245.32				
				supplier	Metals	Copper	7440-50-8		0.154	mg	990000	1585.12				
Bonding wire (Cu)	M-011 Other inorganic materials	0.155	mg	supplier	Metals	Others	Proprietary		0.002	mg	10000	16.01				
				supplier	Metals	Nickel	7440-02-0		1.582	mg	29365	16292.14				
				supplier	Metals	Silicon	7440-21-3		0.350	mg	6500	3606.30				
Leadframe (C194)	M-011 Other inorganic materials	53.878	mg	supplier	Metals	Magnesium	7439-95-4		0.084	mg	1565	868.29				
				supplier	Metals	Silver	7440-22-4		3.394	mg	63000	34953.33				
				supplier	Metals	Copper	7440-50-8		48.467	mg	899570	499094.75				
				supplier	Metals	Nickel (Ni)	7440-02-0		3.385	mg	916800	34862.09				
				supplier	Metals	Palladium (Pd)	7440-05-3		0.217	mg	58700	2232.12				
Leadframe coating (NiPdAu)	M-011 Other inorganic materials	3.693	mg	supplier	Metals	Gold (Au)	7440-57-5		0.090	mg	24500	931.63				